RD-ECR (Engineering Change Request)

申請人: 硬體課/賴嘉賓 表單號: 13 申請日期: 2026-06-09

Proposed Change	☐ Design modification 設計修改 ☐ Add second source 新增替代料 ☐ Material change 材料變更 ☐ Manufacturer change 製造商變更 ☐ Process sequency change 工序變更 ☐ Factory change 工廠變更 ☐ Equipment/Tooling change 設備/模具變更 ☐ Process/Method/Condition change 加工流程/方法 /條件變更 ☑ Others 其他			EC No	EC26060501
-	刪除2nd Source (MCC 用料)			Initiator	賴嘉賓(D0164)
Reason for Change	MCC物料歐盟禁用			Issue Date	2026-06-09
Model / Part No	RUP2732CMI_CTD			Requester Dept	DV11S006-產品管理部
Implementation Type	◉ 1. Immediately Change 立即切換 ○ 2. Running Change 自然切換 ○ 3. Other 其他			-	N/A
PM	曹嘉雯(D0572)	Sales	胡靜文(D0547)	Customer Approval	○ Needed ◉ Not needed
File attached 附件上傳	BAT54 2nd Mail.pdf BAT54 2nd.pdf	Customer Sign-off Area 客戶簽核		Customer Name	Philips
Comments 會簽意見	MCC 物料皆無使用				

Material Change Description 物料變更說明

No	Subassembly	T	PartNo	Description	Qty	Location	Stock	Remark
1	2AAD536R138	B	3DBAT54006Y	DIODE (BAT54C,SOT23,SMD,NXP)	6.000	D305,D310,D311,D312,D313,D901	12,934	
1	2AAD536R138	A	3DBAT54006Y	DIODE (BAT54C,SOT23,SMD,NXP)	6.000	D305,D310,D311,D312,D313,D901	12,934	刪除 2nd source 3DBAT54009Y
2	2AAD536R138	B	3DBAT54008Y	DIODE (BAT54S, SOT23, SMD, NXP)	1.000	D109	12,934	
2	2AAD536R138	A	3DBAT54008Y	DIODE (BAT54S, SOT23, SMD, NXP)	1.000	D109	12,934	刪除 2nd source 3DBAT54019Y

Engineering Change Assessment Item List 工程變更評估項目清單

1. Application for Revision of Specification or Drawing(s) for delivery 是否有修改交貨的規格或圖面	1.Confirm	○ Yes ◉ No need
2. Standards or Regulatories impact 是否有評估適用之標準或主管機關之相關法規的申請	2.Confirm	○ Yes ◉ No need
3. Change point of PCB mounting PCBA插件位置是否變更	3.Confirm	○ Yes ◉ No need
4. PCBA Process Changes PCBA製程是否變更	4.Confirm	○ Yes (Continue checking below) ◉ No
_ 4-1) Change of Reflow temperature 迴焊溫度是否變更	4-1 Confirm	○ Yes ◉ No need
_ 4-2) Change of bonding temperature 膠合溫度是否變更	4-2 Confirm	○ Yes ◉ No need
_ 4-3) Change of Manual Soldering temperature 人工手焊工具之溫度是否變更	4-3 Confirm	○ Yes ◉ No need
_ 4-4) Change of storage condition after protection humidity package 防潮包裝完成後的儲存條件是否變更	4-4 Confirm	○ Yes ◉ No need
5. Reliability test report(Test result and data) 是否有可靠性測試報告(測試結果及數據)	5.Confirm	○ Yes ◉ No need

6. Process FMEA(Medical only) 是否有進行製程失效模式與效應分析	6.Confirm	○ Yes ◉ No need
7. Design FMEA(Medical only) 是否有進行設計失效模式與交應分析	7.Confirm	○ Yes ◉ No need
8. Risk Management(Medical only) 是否有進行風險管理評估	8.Confirm	○ Yes ◉ No need
9. Change points due to the modification 是否此修改會延伸導致其他變更點	9.Confirm	○ Yes ◉ No need
10. Initial Supply Control implements plan or result 是否有實施供料控制評估	10.Confirm	○ Yes ◉ No need
_ 10-1) Confirm the work order or order number or date for the implementation start of the engineering change 確認工程變更開始實施之工單或訂單號碼或日期	10-1 Confirm	○ Yes ◉ No need
_ 10-2) Coordinate the handling methods for related products and materials 協調相關產品及材料處理方法	10-2 Confirm	○ Yes ◉ No need
_ 10-3) Arrange th production schedule 處理生產日程之安排	10-3 Confirm	○ Yes ◉ No need
_ 10-4) Control the changed materials 變更材料之管制	10-4 Confrim	○ Yes ◉ No need
_ 10-5) Establish relevant execution control records for EC materials, register traceability data for each material 建立有關工程變更物料之相關執行管控記錄、登錄各項物料追溯性資料	10-5 Confirm	○ Yes ◉ No need
11. Training Requirement 若此一變更影響製程或檢驗，是否需要再做人員訓練	11.Confrim	○ Yes ◉ No need
12-1. Modification contents(For example, the following documents) 是否有評估此變更之各項相關文件(如下)	12-1 Confirm	☐ QC control plan ☐ Service Manual ☐ Others ☑ Not needed
12-2. Modification contents(For example, the following documents) 是否有評估此變更之各項相關文件(如下)	12-2 Confirm	☐ SIP ☐ SOP ☐ Others ☑ No need
12-3. Modification contents(For example, the following documents) 是否有評估此變更之各項相關文件(如下)	12-3 Confirm	☑ MDF ☑ DMR ☐ Approval Sheet ☐ Engineering Spec ☐ Others ☑ Not needed
DIVA 鈺緯科技開發股份有限公司	版本：C	表單編號：QR-736-05

簽核列表 ◉ 表格 ○ 圖形

序號	簽核人	簽核結果	簽核意見
1	**盧俊宇** 二階主管(課/部級)	**同意** 2026-06-09 08:56	
2	**廖榮棋** DQE	**同意** 2026-06-10 10:22	
3	**胡靜文** Sales	**同意** 2026-06-10 10:31	
3	**曹嘉雯** PM	**同意** 2026-06-10 10:45	
4	**楊建勛** R&D Director [通知]	**同意** 2026-06-10 10:45	[通知]
5	**蕭玉桃** ECR-PIC人員	**同意** 2026-06-10 10:55	
6	**王世炫** ECR-PE人員	**同意** 2026-06-10 11:12	
7	**林益銓** PE	**同意** 2026-06-12 12:14	
8	**黃振哲** ECR-PMC人員	**同意** 2026-06-12 13:51	
9	**邱羽萱** PMC	**同意** 2026-06-12 14:10	
10	**黃瓊玉** ECR-PD人員	**同意** 2026-06-12 14:47	

序號	簽核人	簽核結果	簽核意見
10	**李慧珊** ECR-SCM人員	**同意** 2026-06-12 14:57	
10	**吳汶浦** PD	**同意** 2026-06-17 13:37	
11	**廖映涵** [李慧珊 加簽]	**同意** 2026-06-17 15:13	
12	**李金龍** ECR-QA人員	**同意** 2026-06-17 16:14	
13	**陳泰盛** QA	**同意** 2026-06-18 09:33	
14	**楊建勛** R&D Director	**同意** 2026-06-18 09:37	
15	**蕭玉桃** ECR-PIC人員	**同意** 2026-06-18 10:14	
16	**賴嘉賓** SAP核發	**同意** 2026-06-18 10:23	